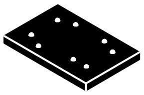
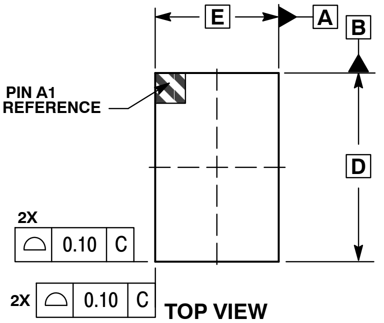
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



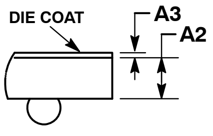
SCALE 4:1

WLCSP8, 3.12x2.04
CASE 567GV
ISSUE B

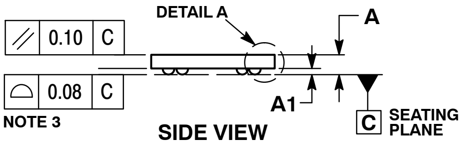
DATE 17 FEB 2014



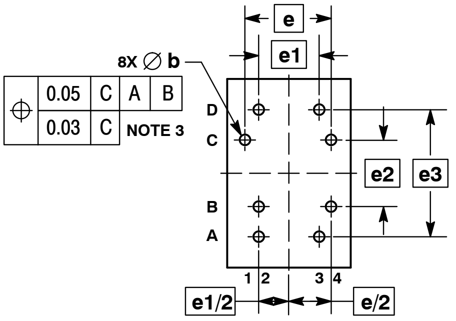
TOP VIEW



DETAIL A



SIDE VIEW

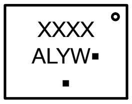


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	---	0.37
A1	0.06	0.10
A2	0.23 REF	
A3	0.025 REF	
b	0.11	0.14
D	3.12 BSC	
E	2.04 BSC	
e	1.40 BSC	
e1	1.00 BSC	
e2	1.10 BSC	
e3	2.10 BSC	

GENERIC MARKING DIAGRAM*

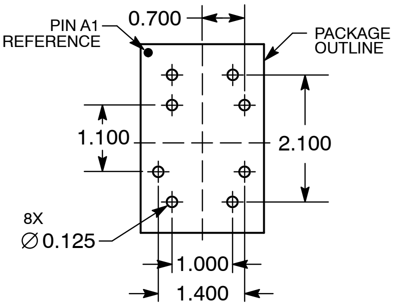


A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**WLCSP8, 3.12X2.04**		**PAGE 1 OF 1**